	IN CHI
REPLY UNDER 37 C.F.R.	§ 1.116
EXPEDITED PROC	EDURE
EXAMINING (GROUP

AMENDMENT TRANSMITTAL LETTER						Docket No. 3313-1048P		
Application No. 10/690,503-Conf. #006047		Filing Date October 23, 2003		Examiner C. F. F. Lam		Art Unit 1775		
Applicant(s): I-Ch	erng CHEN et	al.						
Invention: MATERIAL WITH SURFACE NANOMETER FUNCTIONAL STRUCTURE AND METHOD OF, etc.								
MS AF Commissioner for F P.O. Box 1450 Alexandria, VA 223 Transmitted here The fee has been	313-1450 with is an ame			• •				
			S AS AMENI					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate				
Total Claims	18	- 37 =		х				
Independent Claims	2	- 4 =		x				
Multiple Depend	Multiple Dependent Claims (check if applicable)							
Other fee (pleas	e specify):							
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:						0.00		
X Large Entity Small Entity Small Entity X No additional fee is required for this amendment. Please charge Deposit Account No in the amount of \$ A duplicate copy of this sheet is enclosed. A check in the amount of \$ to cover the filing fee is enclosed. Payment by credit card. Form PTO-2038 is attached. X The Director is hereby authorized to charge and credit Deposit Account No 02-2448 as described below. A duplicate copy of this sheet is enclosed.								
x Credit any overpayment.								
MX	Muncy No.: 32,334 ART, KOLASCH e Rd	H& BIRCH, LL		fees required under 3 Dated:	37 CFR 1.1			



MS AF REPLY UNDER 37 C.F.R. § 1.116 **EXPEDITED PROCEDURE EXAMINING GROUP 1775**

> **PATENT** 3313-1048P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

CHEN, I-Cherng et al.

Conf.:6047

Appl. No.:

10/690,503

Group:

1775

Filed:

October 23, 2003

Examiner: Cathy F.F. LAM

For:

MATERIAL WITH SURFACE NANOMETER FUNCTIONAL

STRUCTURE AND METHOD OF MANUFACTURING THE

SAME

REPLY AFTER FINAL UNDER 37 C.F.R. § 1.116

MS AF

Commissioner for Patents P.O. BOX 1450 Alexandria, VA 22313-1450 May 16, 2005

Sir:

In response to the Examiner's Office Action dated February 14, 2005, Applicants respectfully submit the following amendments and remarks in connection with the above-identified application.

This reply includes

Amendments to the Specification;

Amended Claim set; and

Remarks.